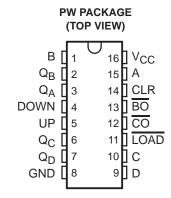
- **Qualified for Automotive Applications**
- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max I_{CC}
- Typical $t_{pd} = 20 \text{ ns}$
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- **Look-Ahead Circuitry Enhances Cascaded** Counters

description/ordering information

The SN74HC193 device is a 4-bit synchronous, reversible, up/down binary counter. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change simultaneously with each other when dictated by the steering logic. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters.

- **Fully Synchronous in Count Modes**
- Parallel Asynchronous Load for Modulo-N **Count Lengths**
- **Asynchronous Clear**



The outputs of the four flip-flops are triggered on a low-to-high-level transition of either count (clock) input (UP or DOWN). The direction of counting is determined by which count input is pulsed while the other count input is high.

All four counters are fully programmable; that is, each output may be preset to either level by placing a low on the load (LOAD) input and entering the desired data at the data inputs. The output changes to agree with the data inputs independently of the count pulses. This feature allows the counters to be used as modulo-N dividers simply by modifying the count length with the preset inputs.

A clear (CLR) input has been provided that forces all outputs to the low level when a high level is applied. The clear function is independent of the count and \overline{LOAD} inputs.

This counter was designed to be cascaded without the need for external circuitry. The borrow (BO) output produces a low-level pulse while the count is zero (all outputs low) and DOWN is low. Similarly, the carry (\overline{CO}) output produces a low-level pulse while the count is maximum (9 or 15), and UP is low. The counter then can be cascaded easily by feeding \overline{BO} and \overline{CO} to DOWN and UP, respectively, of the succeeding counter.

ORDERING INFORMATION[†]

TA	PACKAC	3E‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	TSSOP – PW	Reel of 2000	SN74HC193QPWRQ1	HC193Q
-40°C to 85°C	TSSOP - PW	Reel of 2000	SN74HC193IPWRQ1	HC193I

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

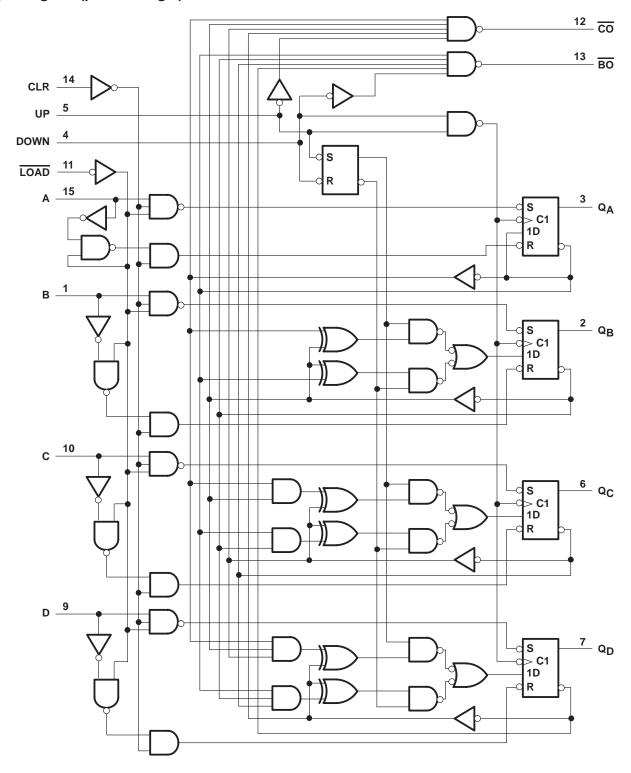


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

logic diagram (positive logic)

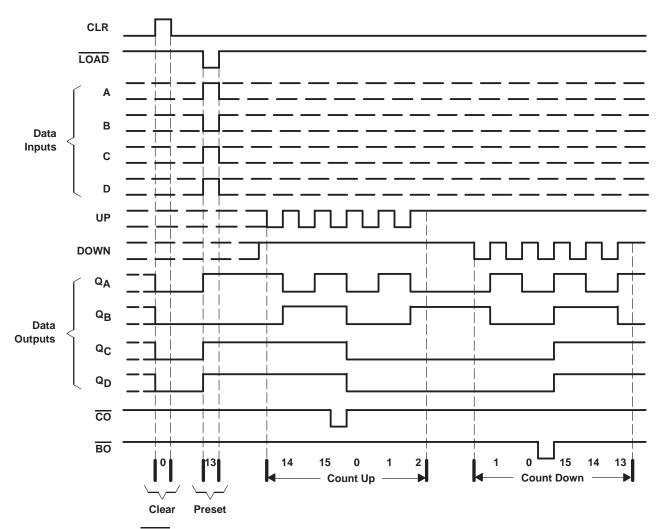




typical clear, load, and count sequence

The following sequence is illustrated below:

- 1. Clear outputs to 0
- 2. Load (preset) to binary 13
- 3. Count up to 14, 15, carry, 0, 1, and 2
- 4. Count down to 1, 0, borrow, 15, 14, and 13



NOTES: A. CLR overrides LOAD, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.



SN74HC193-Q1 **4-BIT SYNCHRONOUS UP/DOWN COUNTER** (DUAL CLOCK WITH CLEAR)

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 7 V
Input clamp current, $I_{ K }(V_{ } < 0 \text{ or } V_{ } > V_{CC})$ (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2)	108°C/W
Storage temperature range, T _{stq}	_65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	V
		V _{CC} = 2 V	1.5			
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			V
		VCC = 6 V	4.2			
		V _{CC} = 2 V			0.5	
VIL	Low-level input voltage $V_{CC} = 4.5 \text{ V}$				1.35	V
		V _{CC} = 6 V			1.8	
٧ _I	Input voltage		0		VCC	V
٧o	Output voltage		0		VCC	V
		V _{CC} = 2 V			1000	
$\Delta t/\Delta v^{\ddagger}$	Input transition rise/fall time	V _{CC} = 4.5 V	500		500	ns
		VCC = 6 V			400	
т.	Q-suffix		-40	40 125	°C	
TA	Operating free-air temperature	I-suffix devices	-40		85	30

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[‡] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at $t_t = 1000$ ns and $V_{CC} = 2$ V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SN74HC193-Q1 4-BIT SYNCHRONOUS UP/DOWN COUNTER (DUAL CLOCK WITH CLEAR) SCLS594A - NOVEMBER 2004 - REVISED APRIL 2008

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		vcc	T _A = 25°C			T _A = -40°C TO 125°C		T _A = -40°C TO 85°C		UNIT
			MIN		TYP	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
VOН	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
	VI = VIH or VIL	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
IĮ	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci		_	2 V to 6 V		3	10		10		10	pF

SN74HC193-Q1 4-BIT SYNCHRONOUS UP/DOWN COUNTER (DUAL CLOCK WITH CLEAR) SCLS594A - NOVEMBER 2004 - REVISED APRIL 2008

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			v _{cc}	T _A = 3	25°C	T _A = -		T _A = -		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V		4.2		2.8		3.3	
fclock	Clock frequency		4.5 V		21		14		17	MHz
			6 V		24		16		19	
			2 V	120		180		150		
		CLR high	4.5 V	24		36		30		
			6 V	21		31		26		
			2 V	120		180		150		
t _w	Pulse duration	LOAD low	4.5 V	24		36		30		ns
			6 V	21		31		26		
			2 V	120		180		150		
		UP or DOWN, high or low	4.5 V	24		36		30		
			6 V	21		31		26		
			2 V	110		165		140		
		Data before LOAD inactive	4.5 V	22		33		28		
			6 V	19		28		24		
			2 V	110		165		140		
t _{su}	Setup time	CLR inactive before UP↑ or DOWN↓	4.5 V	22		33		28		ns
			6 V	19		28		24		
			2 V	110		165		140		
		LOAD inactive before UP↑ or DOWN↓	4.5 V	22		33		28		
			6 V			28		24		
			2 V	5		5		5		
th	Hold time	Data after LOAD inactive	4.5 V	5		5		5		ns
			6 V	5		5		5		

SN74HC193-Q1 **4-BIT SYNCHRONOUS UP/DOWN COUNTER** (DUAL CLOCK WITH CLEAR) SCLS594A - NOVEMBER 2004 - REVISED APRIL 2008

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

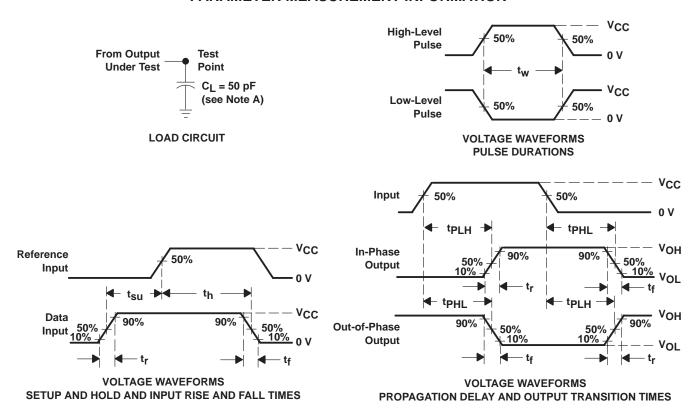
PARAMETER	FROM	TO	v _{CC}	T _A = 25°C			T _A = -		T _A = -40°C TO 85°C		UNIT	
	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	"	
			2 V	4.2	8		2.8		3.3			
f _{max}			4.5 V	21	55		14		17		MHz	
			6 V	24	60		16		19			
			2 V		75	165		250		205		
	UP	CO	4.5 V		24	33		50		41		
			6 V		20	28		43		35		
			2 V		75	165		250		205		
	DOWN	BO	4.5 V		24	33		50		41]	
			6 V		20	28		43		35		
^t pd	UP or DOWN	Any Q	2 V		190	250		375		315	ns	
			4.5 V		40	50		75		63]	
			6 V		35	43		64		54		
			2 V		190	260		390		325		
	LOAD	Any Q	4.5 V		40	52		78		65		
			6 V		35	44		66		55		
			2 V		170	240		360		300		
tPHL	CLR	Any Q	4.5 V		36	48		72		60	ns	
			6 V		31	41		61		51		
			2 V		38	75		110		95		
tt		Any	4.5 V		8	15		22		19	ns	
			6 V		6	14		19		17		

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	50	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



6-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Samples
	(1)		Drawing			(2)		(3)	(Requires Login)
SN74HC193QPWRG4Q1	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC193QPWRQ1	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74HC193-Q1:

Catalog: SN74HC193

Military: SN54HC193

PACKAGE OPTION ADDENDUM

6-Jan-2013

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



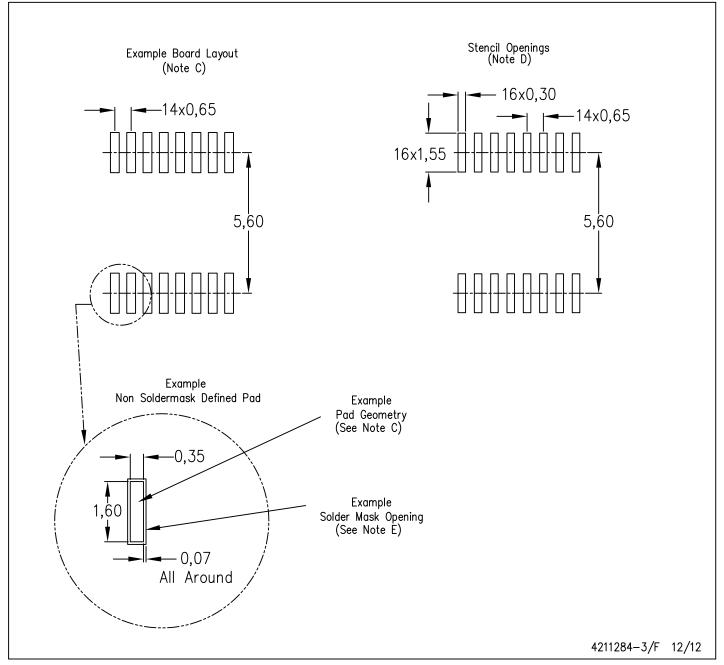
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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